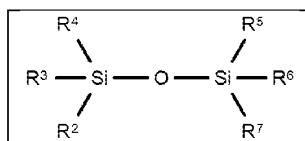


What is claimed is:

1. An article comprising:
 - a first sheet comprising a first sheet bonding surface;
 - a second sheet comprising a second sheet bonding surface; and
 - a coating layer comprising a first coating layer bonding surface and a second coating layer bonding surface, the coating layer comprising a plasma-polymerized organosiloxane compound;

the first coating layer bonding surface is bonded with the first sheet bonding surface, and the second coating layer bonding surface is bonded with the second sheet bonding surface.
2. The article of claim 1, the plasma-polymerized organosiloxane compound formed by depositing a monomer on at least one of the first sheet bonding surface and the second sheet bonding surface.
3. The article of claim 2, the monomer comprising a compound of formula $(R^1)_mSi(X^1)_n$, wherein each R^1 is independently an aryl, alkyl, alkenyl, alkynyl, or a combination thereof; m is 1, 2 or 3; each X^1 is independently hydrogen, halogen, hydroxy, alkoxy, amino, aryl, alkyl, alkenyl, alkynyl, or a combination thereof; and n is 1, 2 or 3.
4. The article of claim 3, R^1 being aryl and/or X^1 being alkoxy.
5. The article of claim 3, wherein the monomer is at least one monomer selected from the group consisting of phenyltrimethoxysilane, phenyltriethoxysilane, phenyltribromosilane, phenyltrichlorosilane, dimethoxydiphenylsilane, diethoxydiphenylsilane, dibromodiphenylsilane, dichlorodiphenylsilane, bis(dimethylamino)diphenylsilane, bis(diethylamino)diphenylsilane, phenylsilane, and diphenylsilane.
6. The article of claim 2, the monomer comprising a disiloxane compound having the structure below, wherein each of R^2 - R^7 is independently hydrogen, halogen, hydroxy, alkoxy, amino, aryl, alkyl, alkenyl, alkynyl, or a combination thereof.



7. The article of claim 6, wherein the monomer is hexamethyldisiloxane.
8. The article of claim 1, the coating layer comprising poly(diphenylsiloxane).
9. The article of any one of claims 1-8, the first coating layer bonding surface having a surface energy between 40 and 75 mJ/m².
10. The article of any one of claims 1-8, the coating layer having a thickness of less than 100 nm.
11. The article of any one of claims 1-8, the coating layer being comprised of a bottom coating layer and a top coating layer, the bottom coating layer being between the top coating layer and the second sheet, the bottom coating layer having a thickness between 10 and 80 nm and the top coating layer having a thickness between 10 and 50 nm.
12. The article of any one of claims 1-8, the first coating layer bonding surface being bonded with the first sheet bonding surface with a bond energy of less than 700 mJ/m² after subjecting the article to a temperature of 600 °C for 10 minutes in a nitrogen atmosphere.
13. The article of any one of claims 1-8, wherein the change in percent blister area is less than 10 when the article is subjected to a temperature of 600 °C for 10 minutes in a nitrogen atmosphere.
14. A method of making an article comprising:
 - forming a coating layer comprising a plasma-polymerized organosiloxane compound on a bonding surface of a second sheet by depositing a monomer on the bonding surface of the second sheet using plasma CVD, the coating layer comprising a coating layer bonding surface; and
 - bonding the coating layer bonding surface to a bonding surface of a first sheet.

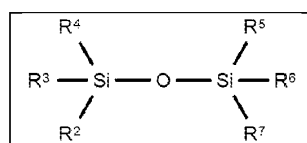
15. The method of claim 14, further comprising exposing the bonding surface to oxygen, nitrogen, or a combination thereof, to increase the surface energy of the coating layer bonding surface before the bonding surface of the first sheet is bonded to the coating layer bonding surface, the surface energy of the coating layer bonding surface being increased to between 40 and 75 mJ/m².

16. The method of claim 14, the monomer comprising a compound of formula (R¹)_mSi(X¹)_n, wherein each R¹ is independently an aryl, alkyl, alkenyl, alkynyl, or a combination thereof; m is 1, 2 or 3; each X¹ is independently, hydrogen, halogen, hydroxy, alkoxy, amino, aryl, alkyl, alkenyl, alkynyl, or a combination thereof; and n is 1, 2 or 3.

17. The method of claim 16, R¹ being aryl and/or X¹ being alkoxy.

18. The method of claim 16, wherein the monomer comprises at least one monomer selected from the group consisting of phenyltrimethoxysilane, phenyltriethoxysilane, phenyltribromosilane, phenyltrichlorosilane, dimethoxydiphenylsilane, diethoxydiphenylsilane, dibromodiphenylsilane, dichlorodiphenylsilane, bis(dimethylamino)diphenylsilane, bis(diethylamino)diphenylsilane, phenylsilane, and diphenylsilane.

19. The method of claim 14, the monomer comprising a disiloxane compound having the structure below, wherein each of R²-R⁷ is independently hydrogen, halogen, hydroxy, alkoxy, amino, aryl, alkyl, alkenyl, alkynyl, or a combination thereof.



20. The method of claim 19, wherein the monomer is hexamethyldisiloxane.

21. The method of claim 14, the coating layer comprising poly(diphenylsiloxane).

22. The method of any one of claims 14-20, the coating layer having a thickness less than 100 nm.

23. The method of any one of claims 14-20, the coating layer being comprised of a bottom coating layer and a top coating layer, the bottom coating layer being between the top coating layer and the second sheet, the bottom coating layer having a thickness between 10 and 80 nm and the top coating layer having a thickness between 10 and 50 nm.

24. The method of any one of claims 14-20, further comprising subjecting the coating layer to thermal annealing, at a temperature of at least 300 °C in a nitrogen atmosphere, before the first sheet and the coating layer are bonded.

25. The method of claim 24, comprising subjecting the coating layer to thermal annealing at a temperature of at least 400 °C.

26. An article comprising:

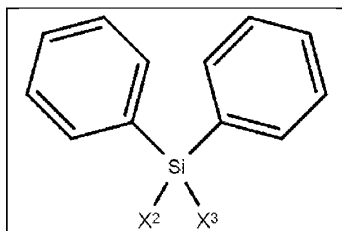
a first sheet comprising a first sheet bonding surface;

a second sheet comprising a second sheet bonding surface; and

a coating layer comprising a first coating layer bonding surface and a second coating layer bonding surface, the coating layer comprising poly(diphenylsiloxane);

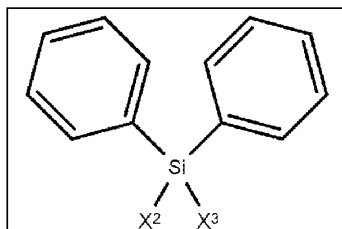
the first coating layer bonding surface is bonded with the first sheet bonding surface, and the second coating layer bonding surface is bonded with the second sheet bonding surface.

27. The article of claim 26, the poly(diphenylsiloxane) coating layer formed by depositing a monomer on at least one of the first sheet bonding surface and the second sheet bonding surface, wherein the monomer is deposited on at least one of the first sheet bonding surface and the second sheet bonding surface, the monomer comprising a diphenylsilane compound having the structure below, wherein X^2 and X^3 are independently hydrogen, halogen, hydroxy, alkoxy, amino, aryl, alkyl, alkenyl, alkynyl, or a combination thereof.



28. The article of claim 26, the first coating layer bonding surface having a surface energy between 40 and 75 mJ/m².
29. The article of any one of claims 26-28, the coating layer having thickness of less than 100 nm.
30. The article of any one of claims 26-28, wherein the coating layer comprises of a bottom coating layer and a top coating layer, and wherein the bottom coating layer is disposed between the top coating layer and the second sheet, the bottom coating layer having a thickness between 10 and 80 nm and the top coating layer having a thickness between 10 and 50 nm.
31. The article of any one of claims 26-28, the first coating layer bonding surface is bonded with the first sheet bonding surface with a bond energy of less than 700 mJ/m² after subjecting the article to a temperature of 600 °C for 10 minutes in a nitrogen atmosphere.
32. The article of any one of claims 26-28, wherein the change in percent blister area is less than 10 when the article is subjected to a temperature of 600 °C for 10 minutes in a nitrogen atmosphere.
33. A method of making an article comprising:
forming a coating layer comprising poly(diphenylsiloxane) on a bonding surface of a second sheet by depositing a monomer on the bonding surface of the second sheet, the coating layer comprising a coating layer bonding surface; and
bonding the coating layer bonding surface to a bonding surface of a first sheet.

34. The method of claim 33, the monomer comprising a diphenylsilane compound having the structure below, wherein X^2 and X^3 are independently hydrogen, halogen, hydroxy, alkoxy, amino, aryl, alkyl, alkenyl, alkynyl, or a combination thereof.



35. The method of claim 33 or claim 34, the coating layer having a thickness less than 100 nm.

36. The method of claim 33 or claim 34, wherein the coating layer is comprised of a bottom coating layer and a top coating layer, the bottom coating layer being between the top coating layer and the second sheet, the bottom coating layer having a thickness between 10 and 80 nm and the top coating layer having a thickness between 10 and 50 nm.

37. The method of claim 33 or claim 34, further comprising subjecting the coating layer to thermal annealing, at a temperature of at least 300 °C in a nitrogen atmosphere, before the first sheet and the coating layer are bonded, comprising subjecting the coating layer to thermal annealing.

38. The method of claim 37, comprising subjecting the coating layer to thermal annealing at a temperature of at least 400 °C.